

To all our customers

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Renesas Technology Corp.  
Customer Support Dept.  
April 1, 2003

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# HM628511HCI Series

Wide Temperature Range Version  
4M High Speed SRAM (512-kword × 8-bit)



ADE-203-1304A (Z)

Rev. 1.0  
Nov. 30, 2001

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## Description

The HM628511HCI Series is a 4-Mbit high speed static RAM organized 512-k word × 8-bit. It has realized high speed access time by employing CMOS process (6-transistor memory cell) and high speed circuit designing technology. It is most appropriate for the application which requires high speed, high density memory and wide bit width configuration, such as cache and buffer memory in system. It is packaged in 400-mil 36-pin plastic SOJ.

## Features

- Single 5.0 V supply: 5.0 V ± 10 %
- Access time: 12 ns (max)
- Completely static memory
  - No clock or timing strobe required
- Equal access and cycle times
- Directly TTL compatible
  - All inputs and outputs
- Operating current: 130 mA (max)
- TTL standby current: 40 mA (max)
- CMOS standby current : 5 mA (max)
- Center  $V_{CC}$  and  $V_{SS}$  type pin out
- Temperature range : -40 to +85°C

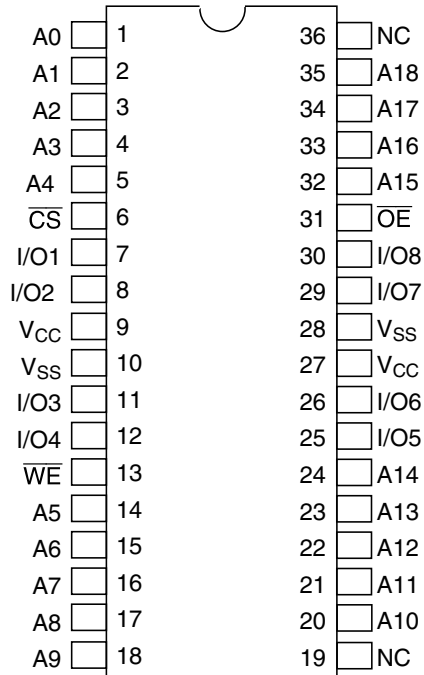
## Ordering Information

Type No.	Access time	Device marking	Package
HM628511HCJPI-12	12 ns	HM628511CJPI12	400-mil 36-pin plastic SOJ (CP-36D)

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## Pin Arrangement

36-pin SOJ

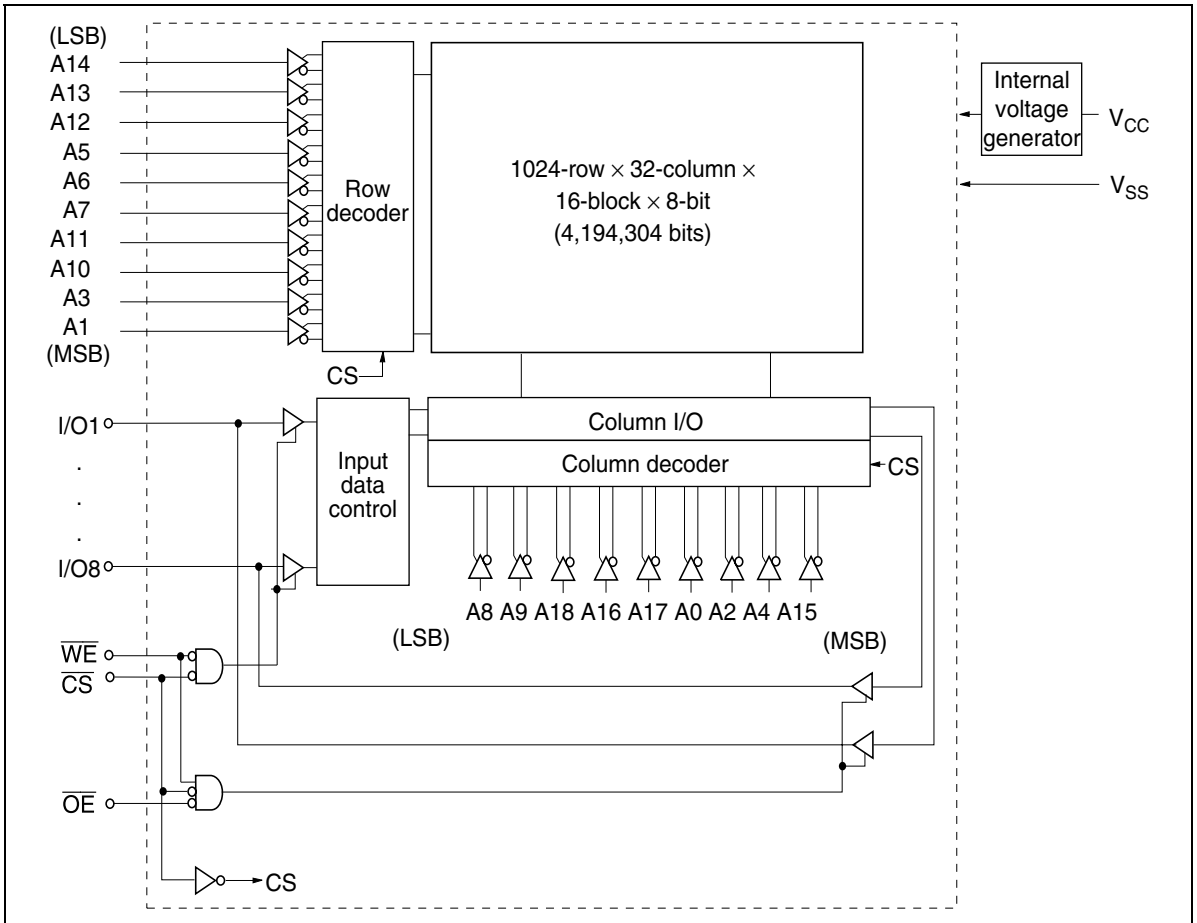


(Top View)

## Pin Description

Pin name	Function
A0 to A18	Address input
I/O1 to I/O8	Data input/output
$\overline{CS}$	Chip select
$\overline{OE}$	Output enable
$\overline{WE}$	Write enable
$V_{CC}$	Power supply
$V_{SS}$	Ground
NC	No connection

Block Diagram



## Operation Table

$\overline{CS}$	$\overline{OE}$	$\overline{WE}$	Mode	$V_{CC}$ current	I/O	Ref. cycle
H	×	×	Standby	$I_{SB}, I_{SB1}$	High-Z	—
L	H	H	Output disable	$I_{CC}$	High-Z	—
L	L	H	Read	$I_{CC}$	Dout	Read cycle (1) to (3)
L	H	L	Write	$I_{CC}$	Din	Write cycle (1)
L	L	L	Write	$I_{CC}$	Din	Write cycle (2)

Note: H:  $V_{IH}$ , L:  $V_{IL}$ , ×:  $V_{IH}$  or  $V_{IL}$

## Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Supply voltage relative to $V_{SS}$	$V_{CC}$	-0.5 to +7.0	V
Voltage on any pin relative to $V_{SS}$	$V_T$	-0.5* <sup>1</sup> to $V_{CC}+0.5$ * <sup>2</sup>	V
Power dissipation	$P_T$	1.0	W
Operating temperature	$T_{opr}$	-40 to +85	°C
Storage temperature	$T_{stg}$	-55 to +125	°C
Storage temperature under bias	$T_{bias}$	-40 to +85	°C

Notes: 1.  $V_T$  (min) = -2.0 V for pulse width (under shoot) ≤ 6 ns.

2.  $V_T$  (max) =  $V_{CC}+2.0$  V for pulse width (over shoot) ≤ 6 ns.

## Recommended DC Operating Conditions

( $T_a = -40$  to +85°C)

Parameter	Symbol	Min	Typ	Max	Unit
Supply voltage	$V_{CC}$ * <sup>3</sup>	4.5	5.0	5.5	V
	$V_{SS}$ * <sup>4</sup>	0	0	0	V
Input voltage	$V_{IH}$	2.2	—	$V_{CC} + 0.5$ * <sup>2</sup>	V
	$V_{IL}$	-0.5* <sup>1</sup>	—	0.8	V

Notes: 1.  $V_{IL}$  (min) = -2.0 V for pulse width (under shoot) ≤ 6 ns.

2.  $V_{IH}$  (max) =  $V_{CC}+2.0$  V for pulse width (over shoot) ≤ 6 ns.

3. The supply voltage with all  $V_{CC}$  pins must be on the same level.

4. The supply voltage with all  $V_{SS}$  pins must be on the same level.

## DC Characteristics

( $T_a = -40$  to  $+85^\circ\text{C}$ ,  $V_{CC} = 5.0\text{ V} \pm 10\%$ ,  $V_{SS} = 0\text{V}$ )

Parameter	Symbol	Min	Typ* <sup>1</sup>	Max	Unit	Test conditions
Input leakage current	$ I_{LI} $	—	—	2	$\mu\text{A}$	$V_{in} = V_{SS}$ to $V_{CC}$
Output leakage current	$ I_{LO} $	—	—	2	$\mu\text{A}$	$V_{in} = V_{SS}$ to $V_{CC}$
Operation power supply current	$I_{CC}$	—	—	130	mA	Min cycle $\overline{CS} = V_{IL}$ , $I_{out} = 0\text{ mA}$ Other inputs = $V_{IH}/V_{IL}$
Standby power supply current	$I_{SB}$	—	—	40	mA	Min cycle, $\overline{CS} = V_{IH}$ , Other inputs = $V_{IH}/V_{IL}$
	$I_{SB1}$	—	2.5	5	mA	$f = 0\text{ MHz}$ $V_{CC} \geq \overline{CS} \geq V_{CC} - 0.2\text{ V}$ , (1) $0\text{ V} \leq V_{in} \leq 0.2\text{ V}$ or (2) $V_{CC} \geq V_{in} \geq V_{CC} - 0.2\text{ V}$
Output voltage	$V_{OL}$	—	—	0.4	V	$I_{OL} = 8\text{ mA}$
	$V_{OH}$	2.4	—	—	V	$I_{OH} = -4\text{ mA}$

Notes: 1. Typical values are at  $V_{CC} = 5.0\text{ V}$ ,  $T_a = +25^\circ\text{C}$  and not guaranteed.

## Capacitance

( $T_a = +25^\circ\text{C}$ ,  $f = 1.0\text{ MHz}$ )

Parameter	Symbol	Min	Typ	Max	Unit	Test conditions
Input capacitance* <sup>1</sup>	$C_{in}$	—	—	6	pF	$V_{in} = 0\text{ V}$
Input/output capacitance* <sup>1</sup>	$C_{I/O}$	—	—	8	pF	$V_{I/O} = 0\text{ V}$

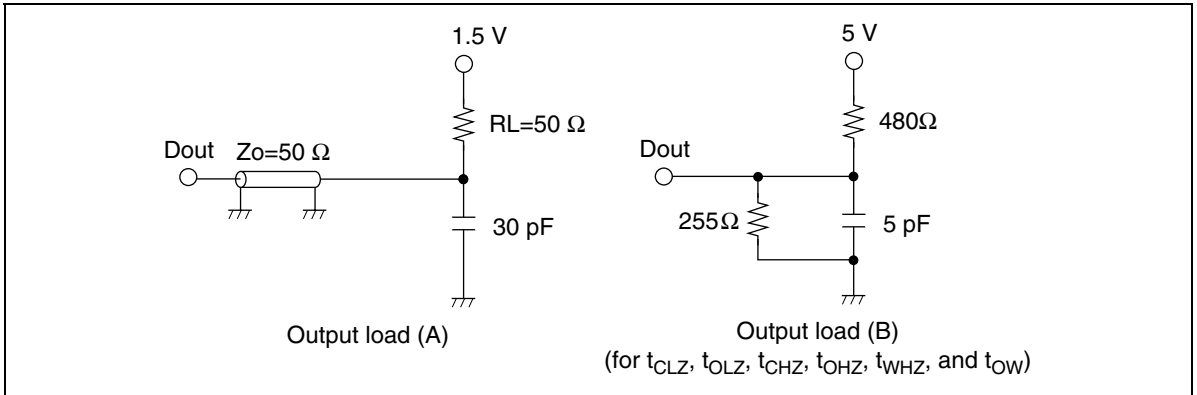
Note: 1. This parameter is sampled and not 100% tested.

## AC Characteristics

( $T_a = -40$  to  $+85^\circ\text{C}$ ,  $V_{CC} = 5.0\text{ V} \pm 10\%$ , unless otherwise noted.)

### Test Conditions

- Input pulse levels: 3.0 V/0.0 V
- Input rise and fall time: 3 ns
- Input and output timing reference levels: 1.5 V
- Output load: See figures (Including scope and jig)



### Read Cycle

Parameter	Symbol	HM628511HCI		Unit	Notes
		Min	Max		
Read cycle time	$t_{RC}$	12	—	ns	
Address access time	$t_{AA}$	—	12	ns	
Chip select access time	$t_{ACS}$	—	12	ns	
Output enable to output valid	$t_{OE}$	—	6	ns	
Output hold from address change	$t_{OH}$	3	—	ns	
Chip select to output in low-Z	$t_{CLZ}$	3	—	ns	1
Output enable to output in low-Z	$t_{OLZ}$	0	—	ns	1
Chip deselect to output in high-Z	$t_{CHZ}$	—	6	ns	1
Output disable to output in high-Z	$t_{OHZ}$	—	6	ns	1



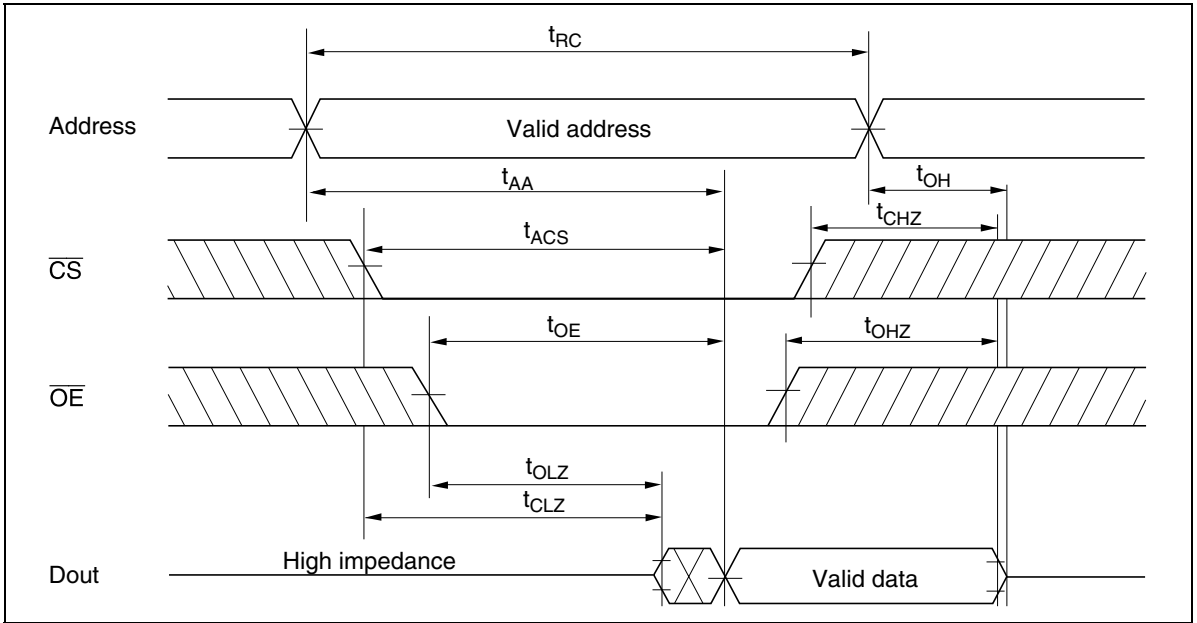
## Write Cycle

Parameter	Symbol	HM628511HCI			Notes
		-12			
		Min	Max	Unit	
Write cycle time	$t_{WC}$	12	—	ns	
Address valid to end of write	$t_{AW}$	8	—	ns	
Chip select to end of write	$t_{CW}$	8	—	ns	9
Write pulse width	$t_{WP}$	8	—	ns	8
Address setup time	$t_{AS}$	0	—	ns	6
Write recovery time	$t_{WR}$	0	—	ns	7
Data to write time overlap	$t_{DW}$	6	—	ns	
Data hold from write time	$t_{DH}$	0	—	ns	
Write disable to output in low-Z	$t_{OW}$	3	—	ns	1
Output disable to output in high-Z	$t_{OHZ}$	—	6	ns	1
Write enable to output in high-Z	$t_{WHZ}$	—	6	ns	1

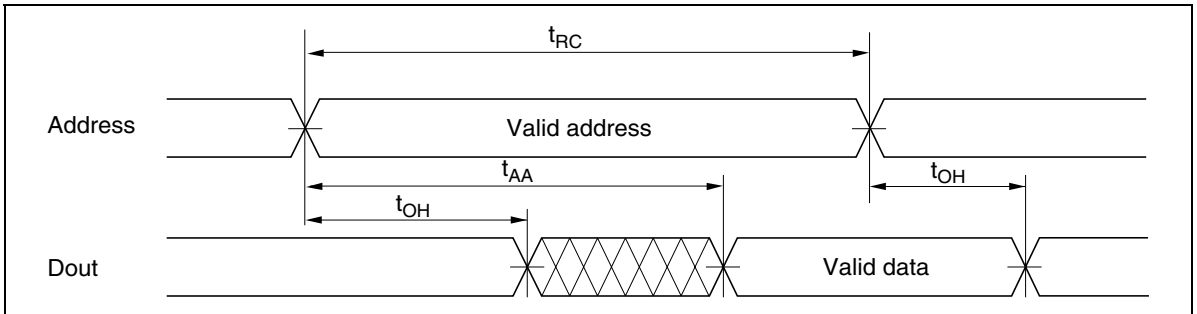
- Notes:
1. Transition is measured  $\pm 200$  mV from steady voltage with output load (B). This parameter is sampled and not 100% tested.
  2. Address should be valid prior to or coincident with  $\overline{CS}$  transition low.
  3.  $\overline{WE}$  and/or  $\overline{CS}$  must be high during address transition time.
  4. If  $\overline{CS}$  and  $\overline{OE}$  are low during this period, I/O pins are in the output state. Then, the data input signals of opposite phase to the outputs must not be applied to them.
  5. If the  $\overline{CS}$  low transition occurs simultaneously with the  $\overline{WE}$  low transition or after the  $\overline{WE}$  transition, output remains a high impedance state.
  6.  $t_{AS}$  is measured from the latest address transition to the later of  $\overline{CS}$  or  $\overline{WE}$  going low.
  7.  $t_{WR}$  is measured from the earlier of  $\overline{CS}$  or  $\overline{WE}$  going high to the first address transition.
  8. A write occurs during the overlap of a low  $\overline{CS}$  and a low  $\overline{WE}$ . A write begins at the latest transition among  $\overline{CS}$  going low and  $\overline{WE}$  going low. A write ends at the earliest transition among  $\overline{CS}$  going high and  $\overline{WE}$  going high.  $t_{WP}$  is measured from the beginning of write to the end of write.
  9.  $t_{CW}$  is measured from the later of  $\overline{CS}$  going low to the end of write.

## Timing Waveforms

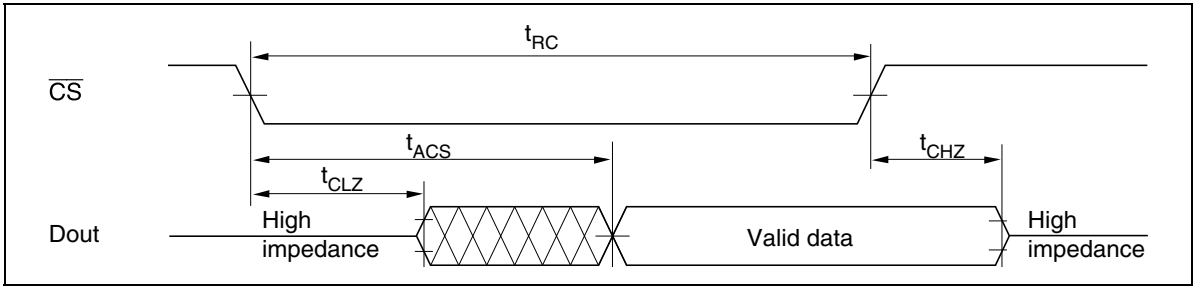
Read Timing Waveform (1) ( $\overline{WE} = V_{IH}$ )



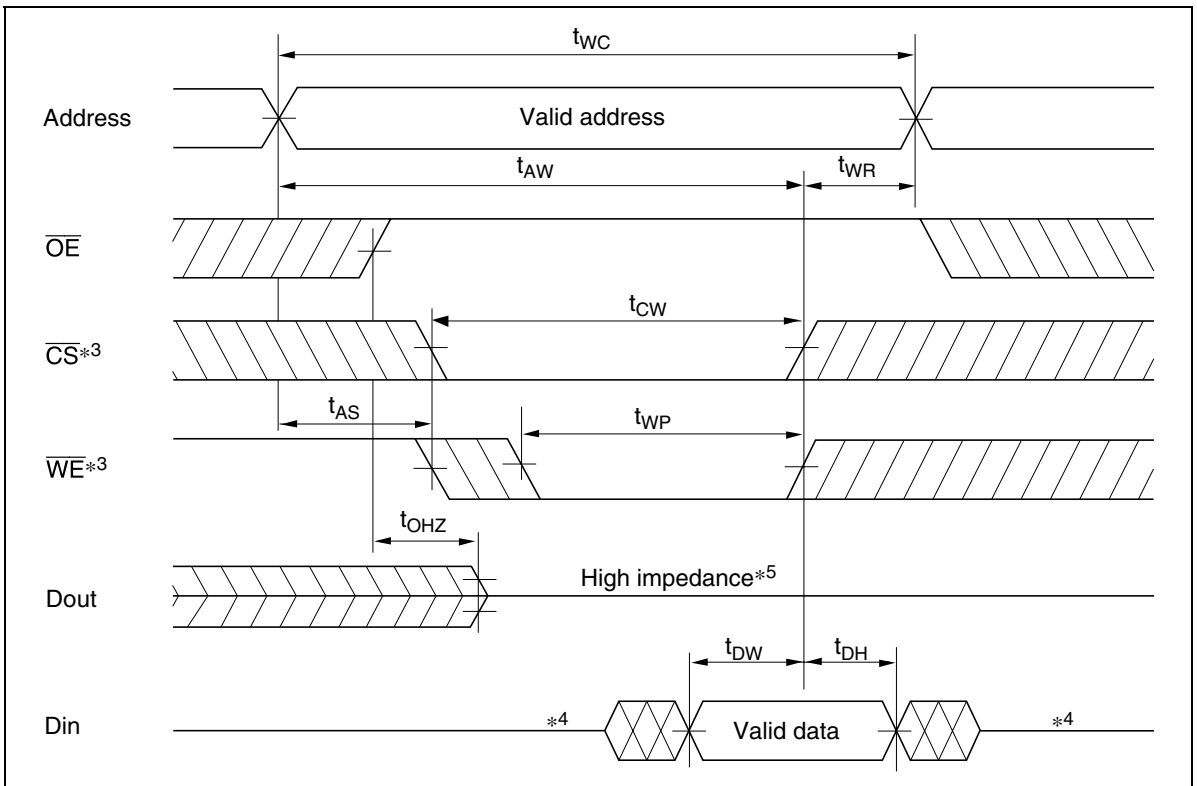
Read Timing Waveform (2) ( $\overline{WE} = V_{IH}$ ,  $\overline{CS} = V_{IL}$ ,  $\overline{OE} = V_{IL}$ )



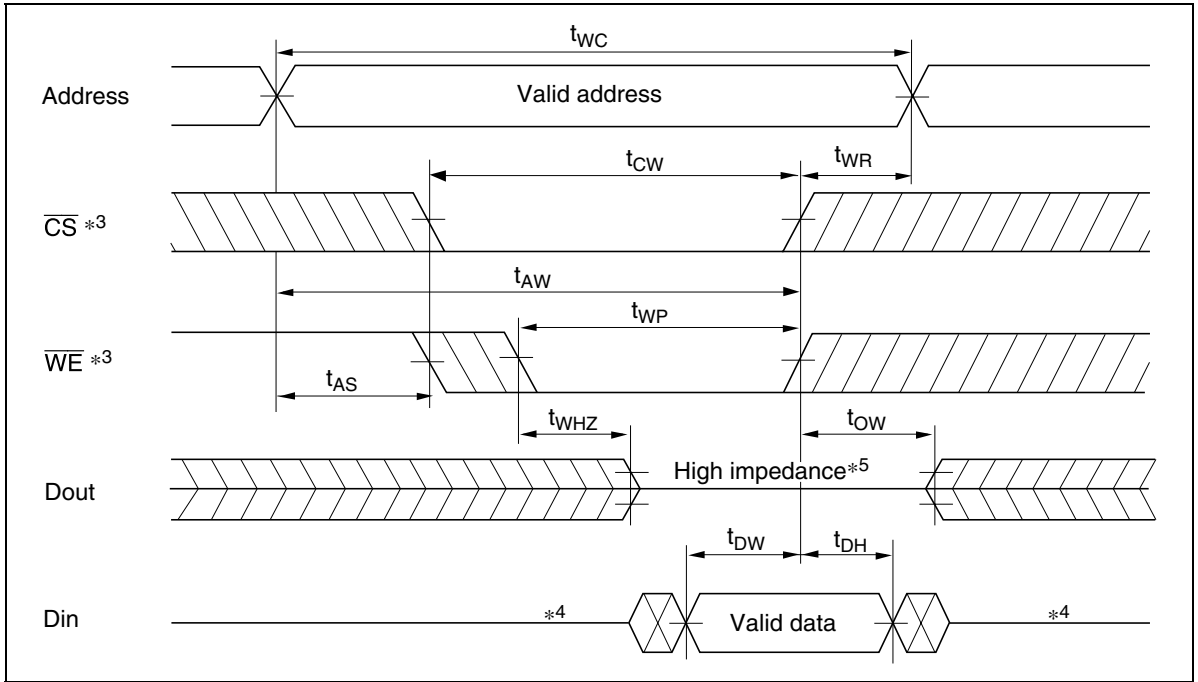
Read Timing Waveform (3) ( $\overline{WE} = V_{IH}, \overline{CS} = V_{IL}, \overline{OE} = V_{IL}$ )\*<sup>2</sup>



Write Timing Waveform (1) ( $\overline{WE}$  Controlled)



## Write Timing Waveform (2) ( $\overline{CS}$ Controlled)

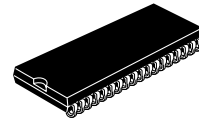
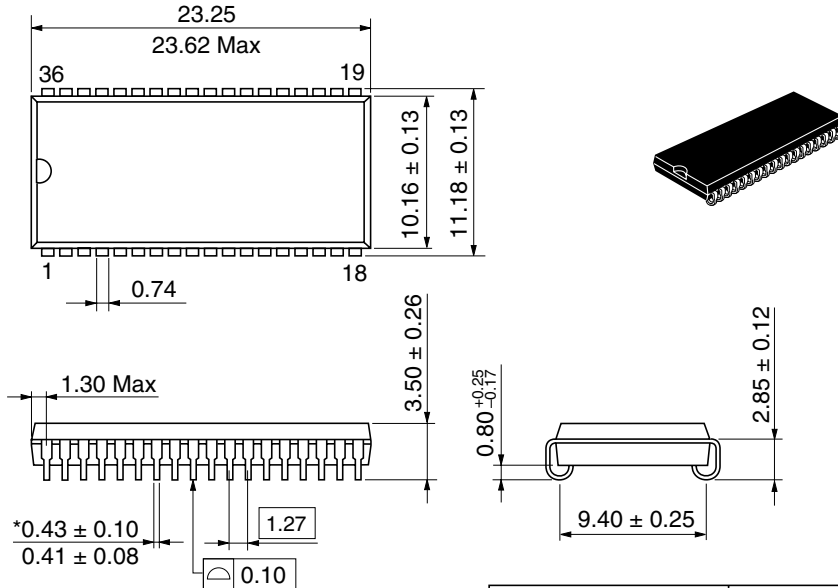


## Package Dimensions

### HM628511HCJPI Series (CP-36D)

As of January, 2001

Unit: mm



\*Dimension including the plating thickness  
Base material dimension

Hitachi Code	CP-36D
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	1.4 g

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